µClamp0511Z
Ultra Small µClamp®
1 Line, 5V ESD Protection

PROTECTION PRODUCTS

Description

µClamp® TVS diodes are designed to protect sensitive electronics from damage or latch-up due to ESD. They features large cross-sectional area junctions for conducting high transient currents. These devices offer desirable characteristics for board level protection including fast response time, low operating and clamping voltage,and no device degradation.

The µClamp®0511Z is in a 2-pin SLP0603P2X3 package. It measures 0.6 x 0.3 mm with a nominal height of only 0.25mm. The leads are finished with lead-free NiAu. Each device will protect one line operating at 5 volts. It gives the designer the flexibility to protect single lines in applications where arrays are not practical. The combination of small size and high ESD surge capability makes them ideal for use in portable applications such as cellular phones, digital cameras, and tablet PC's.

Features

- High ESD withstand Voltage: +/-15kV (Air) and +/-8kV (contact) per IEC 61000-4-2
- Able to withstand over 1000 ESD strikes per IEC61000-4-2 Level 4
- Ultra-small 0201 package
- Protects one data line or power line
- Low leakage current: <10nA (V_R=5V)
- Working voltage: +/-5V
- Low dynamic resistance: 0.64 Ω (typ)
- Solid-state silicon-avalanche technology

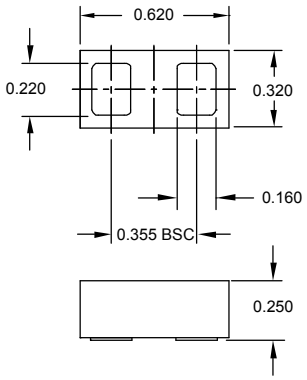
Mechanical Characteristics

- SLP0603P2X3 package
- Pb-Free, Halogen Free, RoHS/WEEE compliant
- Nominal Dimensions: 0.6 x 0.3 x 0.25 mm
- Lead Finish: NiAu
- Marking: Marking code + dot matrix date code
- Packaging: Tape and Reel

Applications

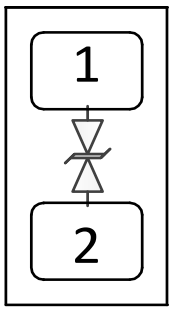
- Cellular Handsets & Accessories
- Keypads, Side Keys, Audio Ports
- Portable Instrumentation
- Digital Lines
- MP3 Players

Package Dimension



Nominal Dimensions (mm)

Schematic & Pin Configuration



SLP0603P2X3 (Bottom View)

Absolute Maximum Rating

Rating	Symbol	Value	Units
ESD per IEC 61000-4-2 (Air)(2) ESD per IEC 61000-4-2 (Contact)(2)	V_{ESD}	±15 ±8	kV
Operating Temperature	T_J	-55 to +125	°C
Storage Temperature	T_{STG}	-55 to +150	°C

Electrical Characteristics (T=25°C unless otherwise specified)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Units
Reverse Stand-Off Voltage	V_{RWM}	Pin1 to 2 or 2 to 1				5	V
Reverse Breakdown Voltage	V_{BR}	I_t = 1mA, Pin 1 to 2 or 2 to 1		6	8.2	9.5	V
Reverse Leakage Current	I_R	V_{RWM} = 5V, Pin 1 to 2 or 2 to 1			3	50	nA
Clamping Voltage	V_C	I_{PP}=1A, tp = 8/20µs, Pin1 to 2 or 2 to 1				15	V
ESD Clamping Voltage[2]	V_C	t_p = 0.2/100ns	I_{PP} = 4A		11.2		V
			I_{PP} = 16A		19.4		
Dynamic Resistance[2,3]	R_{DYN}	t_p = 0.2/100ns			0.64		Ω
Junction Capacitance	C_J	V_R = 0V, f = 1MHz	T = 25°C		4	7	pF

Notes

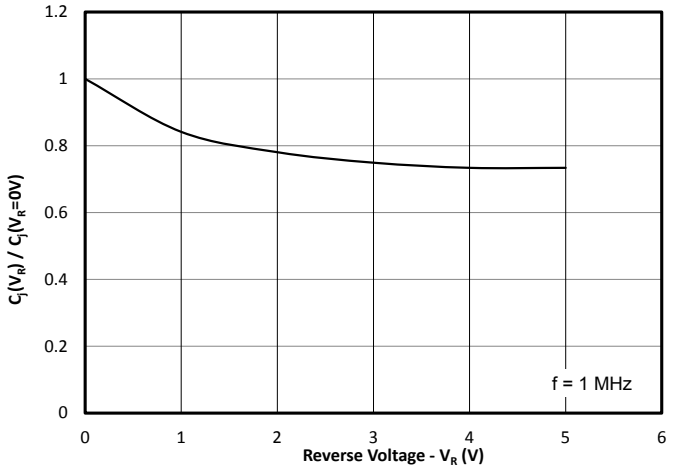
1) Measured with a 20dB attenuator, 50 Ohm scope input impedance, 2GHz bandwidth. ESD gun return path connected to ESD ground plane.

2) Transmission Line Pulse Test (TLP) Settings: tp = 100ns, tr = 0.2ns, I_{TLP} and V_{TLP} averaging window: t1 = 70ns to t2 = 90ns.

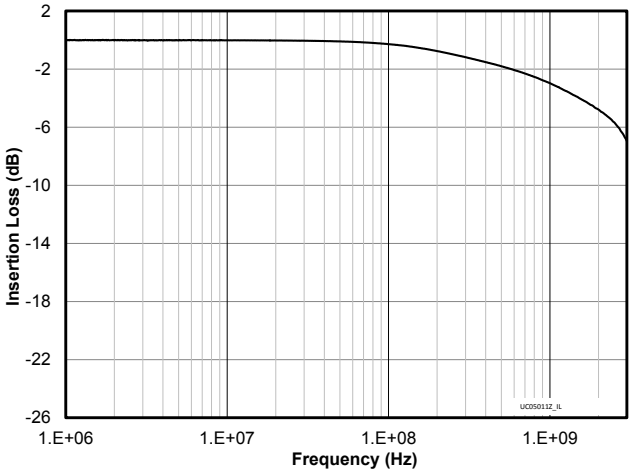
3) Dynamic resistance calculated from I_{TLP} = 4A to I_{TLP} = 16A

Typical Characteristics

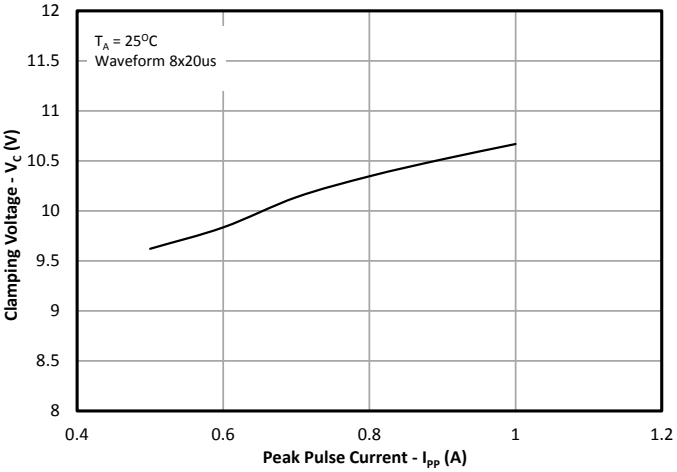
Normalized Junction Capacitance vs. Reverse Voltage



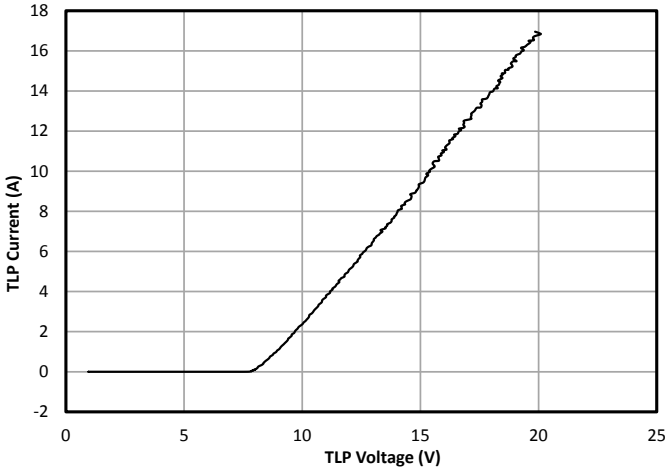
Insertion Loss-S21



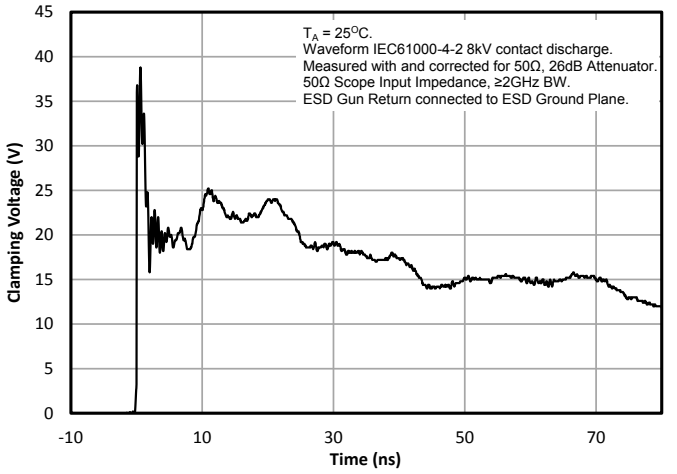
Clamping Voltage vs. Peak Pulse Current (tp=8/20 µs)



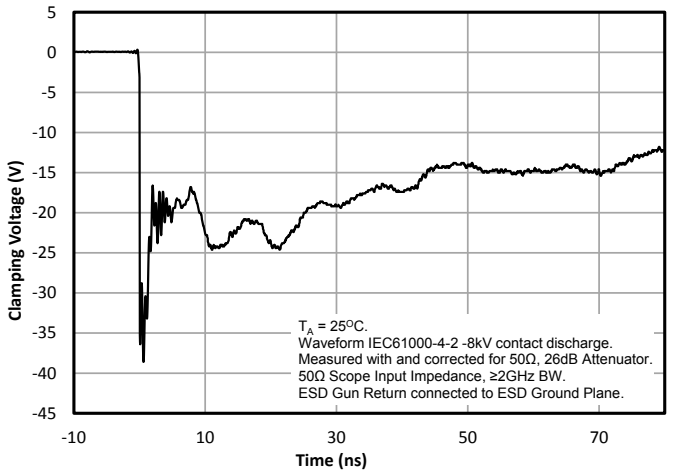
TLP Characteristic (Positive Pulse)



ESD Clamping (8kV Contact per IEC 61000-4-2)



ESD Clamping (-8kV Contact per IEC 61000-4-2)



Application Information

Assembly Guidelines

The small size of this device means that some care must be taken during the mounting process to insure reliable-solder joints. The figure at the right details Semtech's recommended mounting pattern. Recommended assembly guidelines are shown in Table 1. Note that these are only recommendations and should serve only as a starting point for design since there are many factors that affect the assembly process. Exact manufacturing-parameters will require some experimentation to get the desired solder application. Semtech's recommend-edmounting pattern is based on the following design guidelines:

Land Pattern

The recommended land pattern follows IPC standards and is designed for maximum solder coverage. Detailed dimensions are shown elsewhere in this document.

Solder Stencil

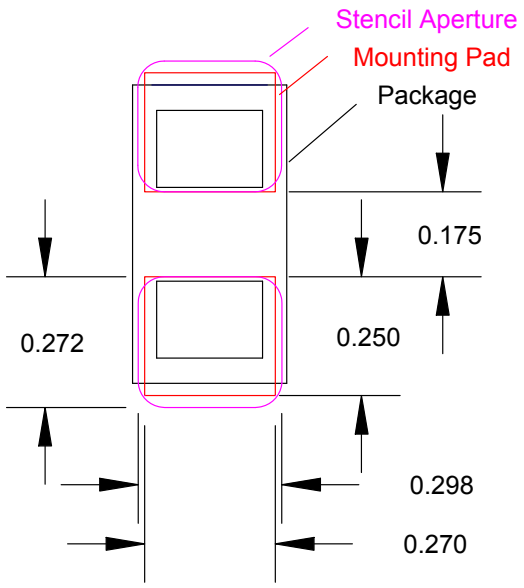
Stencil design is one of the key factors which will determine the volume of solder paste which is deposited onto the land pad. The area ratio of the stencil aperture will determine how well the stencil will print. The area ratio takes into account the aperture shape, aperture size, and stencil thickness. An area
ratio of 0.70 – 0.75 is preferred for the subject package. The area ratio of a rectangular aperture is given as:

Area Ratio = (L * W)/ (2 * (L + W) * T)

Where:
L = Aperture Length
W = Aperture Width
T = Stencil Thickness

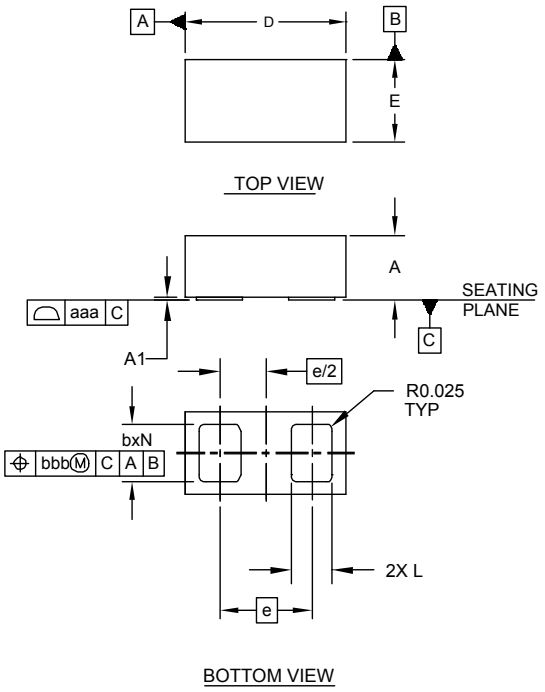
Semtech recommends a stencil thickness of 0.100mm for this device. The stencil should be laser cut with electrop-olishedfinish. The stencil should have a positive taper of approximately 5 degrees. Electro polishing and tapering the walls results in reduced surface friction and better paste release. For small pitch components, Semtech recommends a square aperture with rounded corners for consistent solder release. Due to the small aperture size, a solder paste with Type 4 or smaller particles are recom-mended.

Recommended Mounting Pattern



Assembly Parameter	Recommendation
Solder Stencil Design	Laser cut, Electro-polished
Aperture shape	Rectangular with rounded corners
Solder Stencil Thickness	0.100 mm (0.004")
Solder Paste Type	Type 4 size sphere or smaller
Solder Reflow Profile	Per JEDEC J-STD-020
PCB Solder Pad Design	Non-Solder mask defined
PCB Pad Finish	OSP OR NiAu

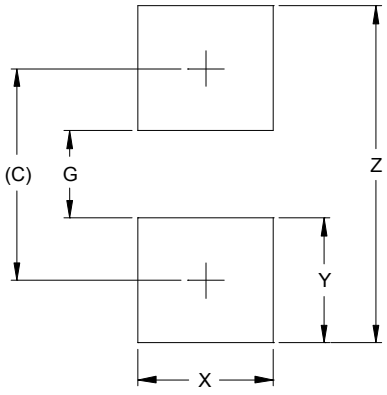
Outline Drawing - SLP0603P2X3



DIMENSIONS			
DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.235	0.250	0.265
A1	0.000	0.02	0.025
b	0.20	0.22	0.24
D	0.585	0.62	0.655
E	0.285	0.32	0.355
e	0.355 BSC		
L	0.140	0.160	0.180
N	2		
aaa	0.08		
bbb	0.10		

NOTES:
1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).

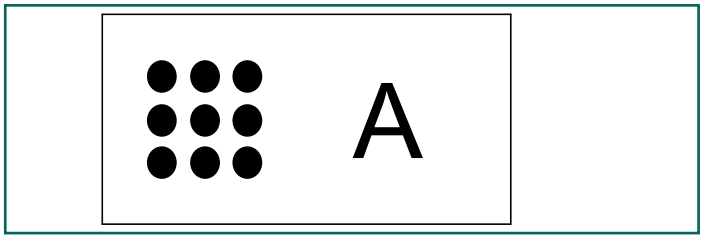
Land Pattern - SLP0603P2X3



DIMENSIONS	
DIM	MILLIMETERS
C	(0.425)
G	0.175
X	0.270
Y	0.250
Z	0.675

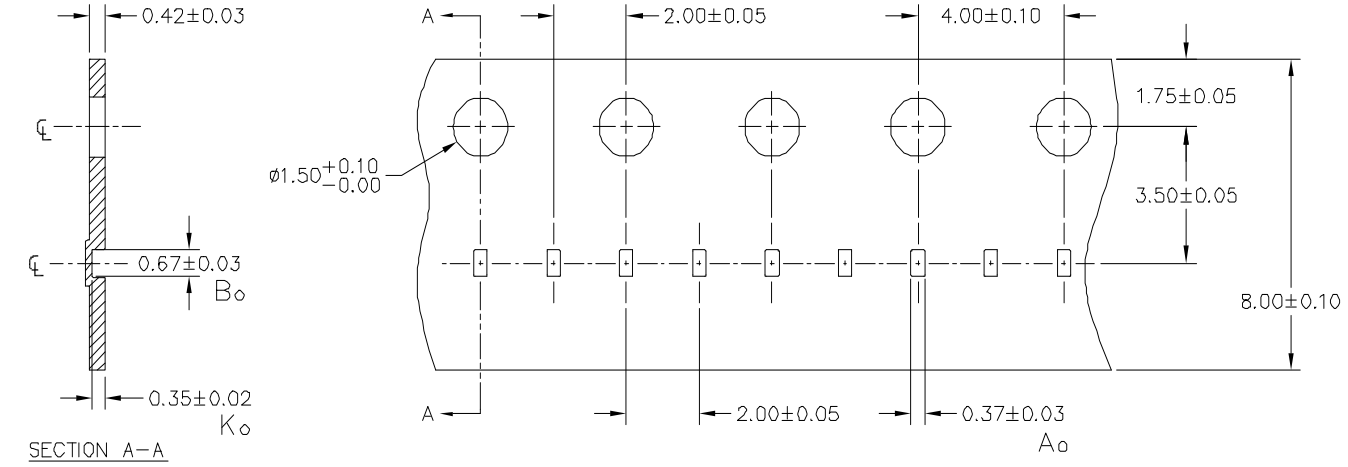
NOTES:
1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY.
CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR
COMPANY'S MANUFACTURING GUIDELINES ARE MET.

Marking Code

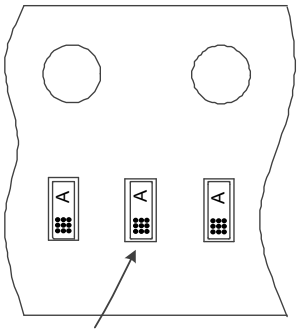


Note: Dots represent date code matrix

Tape and Reel Specification - Paper Tape

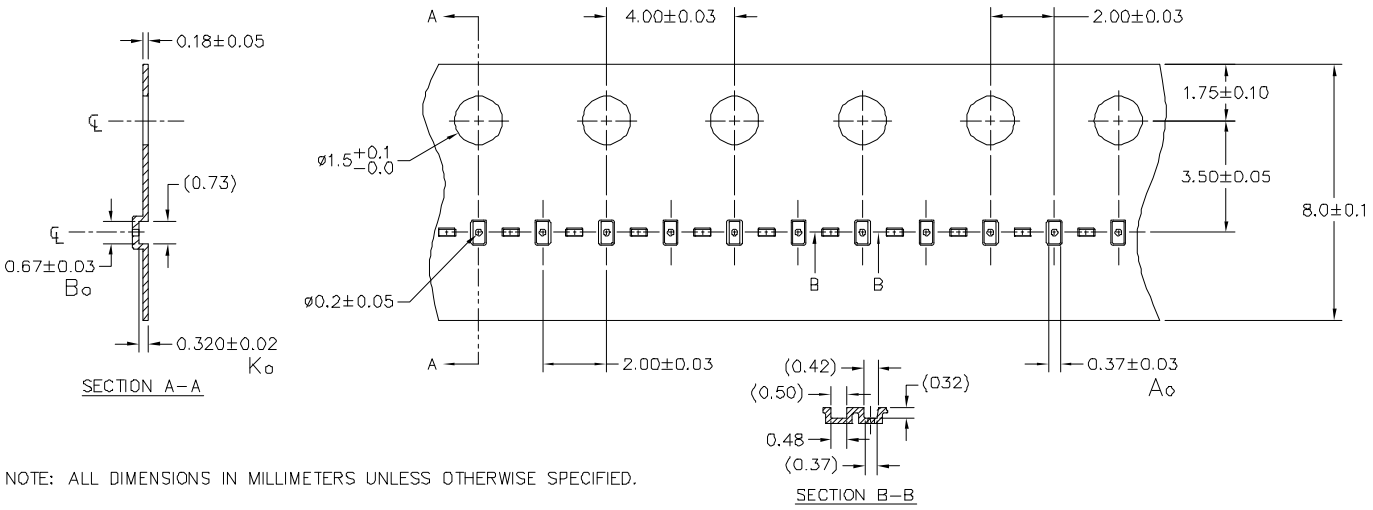


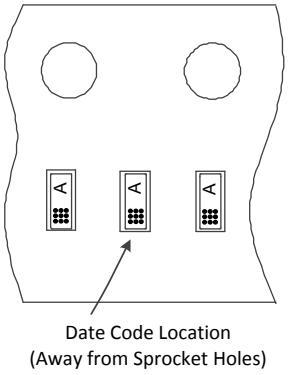
NOTES: ALL DIMENSIONS IN MILLIMETERS UNLESS OTHERWISE SPECIFIED.



Date Code Location
(Away from Sprocket Holes)

Tape and Reel Specification-Plastic Tape





Ordering Information

Part Number	Qty per Reel	Carrier Tape	Reel Size
µClamp0511Z.TFT	15,000	Paper	7″
µClamp0511Z.TNT	10,000	Plastic	7″